

RCJ081N20

Nch 200V 8.0A Power MOSFET

V_{DSS}	200V
R _{DS(on)} (Max.)	770m $Ω$
I _D	8.0A
P_{D}	40W

Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

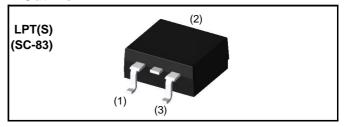
Application

Switching Power Supply

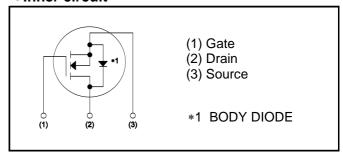
Automotive Motor Drive

Automotive Solenoid Drive

Outline



●Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Typo	Tape width (mm)	24
Type	Quantity (pcs)	1,000
	Taping code	TL
	Marking	RCJ081N20

• Absolute maximum ratings $(T_a = 25^{\circ}C)$

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V_{DSS}	200	V	
Continuous drain current	T _c = 25°C	I _D *1	±8.0	A
Continuous drain current	T _c = 100°C	I _D *1	±4.3	A
Pulsed drain current	I _{D,pulse} *2	±32	А	
Gate - Source voltage	V_{GSS}	±30	V	
Avalanche energy, single pulse		E _{AS} *3	5.17	mJ
Avalanche current		I _{AR} *3	4.0	А
$T_c = 25$ °C		P _D	40	W
Power dissipation $T_a = 25^{\circ}C^{*4}$		P _D	1.56	W
Junction temperature	T _j	150	°C	
Range of storage temperature		T _{stg}	−55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
raiametei	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	1	-	3.125	°C/W
Thermal resistance, junction - ambient *4	R_{thJA}	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T_{sold}	ı	1	265	°C

•Electrical characteristics($T_a = 25$ °C)

Parameter	Symbol Conditions		Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	200	-	-	V
Zoro gato voltago drain current	la ca	$V_{DS} = 200V, V_{GS} = 0V$ $T_j = 25^{\circ}C$	ı	ı	10	^
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 200V, V_{GS} = 0V$ $T_j = 125^{\circ}C$	ı	ı	100	μΑ
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V$, $I_D = 1mA$	3.25	-	5.25	V
		$V_{GS} = 10V, I_D = 4.0A$	-	550	770	
Static drain - source on - state resistance	R _{DS(on)} *5	$V_{GS} = 10V, I_D = 4.0A$ $T_j = 125^{\circ}C$	-	1100	1540	mΩ
Forward transfer admittance	g _{fs}	$V_{DS} = 10V, I_{D} = 4.0A$	1.0	2.0	-	S

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	330	-	
Output capacitance	C_{oss}	V _{DS} = 25V	-	33	1	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	15	-	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 100 \text{V}, V_{GS} = 10 \text{V}$	-	13	-	
Rise time	t _r *5	$I_{D} = 4.0A$	-	20	-	no
Turn - off delay time	t _{d(off)} *5	$R_L = 25\Omega$	-	18	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	8	-	

•Gate Charge characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	bol Conditions -		Тур.	Max.	Offic
Total gate charge	Q_g^{*5}	$V_{DD} \simeq 100V$	-	8.5	-	
Gate - Source charge	Q_{gs}^{*5}	I _D = 8.0A	-	3.4	1	nC
Gate - Drain charge	Q_{gd}^{*5}	V _{GS} = 10V	-	3.4	ı	
Gate plateau voltage	V _(plateau)	$V_{DD} \approx 100V, I_D = 8.0A$	-	7.9	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol Conditions			Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous source current	l _S *1	T _c = 25°C	-	-	8.0	Α
Pulsed source current	I _{SM} *2	1 _c = 23 C	-	-	32	Α
Forward voltage	V _{SD} *5	$V_{GS} = 0V, I_{S} = 8.0A$	-	-	1.5	V
Reverse recovery time	t _{rr} *5	I _S = 4.0A	-	75	-	ns
Reverse recovery charge	Q _{rr} *5	di/dt = 100A/μs	-	210	-	nC

^{*1} Limited only by maximum temperature allowed.

*5 Pulsed

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L $^{\simeq}$ 500 μ H, V_{DD} = 50V, Rg = 25 Ω , starting T $_{j}$ = 25°C

^{*4} Mounted on a epoxy PCB FR4 (25mm × 27mm × 0.8mm)

Fig.1 Power Dissipation Derating Curve

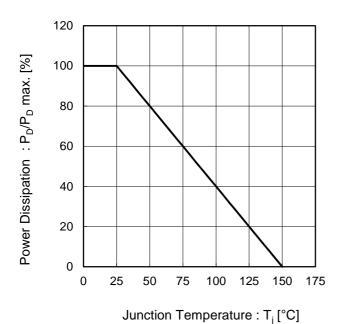
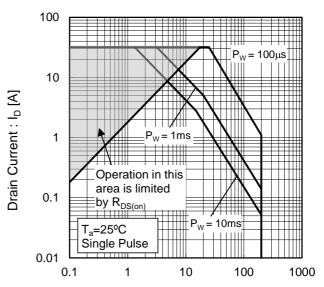
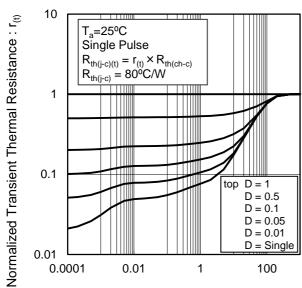


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width: Pw[s]

Fig.4 Avalanche Current vs Inductive Load

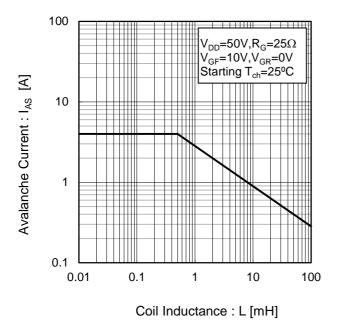
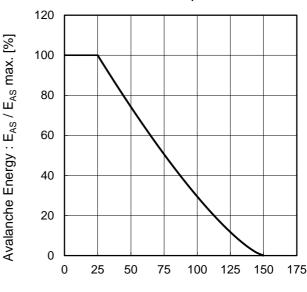
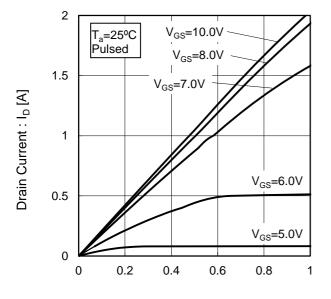


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



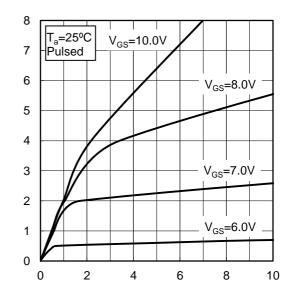
Junction Temperature : T_i [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

Fig.7 Typical Output Characteristics(II)

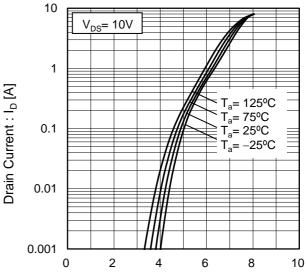


Drain - Source Voltage : V_{DS} [V]

Drain Current : I_D [A]

Fig.8 Breakdown Voltage vs. Junction Temperature 280 Normarize Drain - Source Breakdown Voltage $V_{GS} = 0V$ 270 $I_D = 1 \text{mA}$ 260 250 240 230 220 210 200 190 180 -50 0 50 100 150 Junction Temperature : T_i [°C]

Fig.9 Typical Transfer Characteristics



Gate - Source Voltage : V_{GS} [V]

Fig.10 Gate Threshold Voltage vs. Junction Temperature

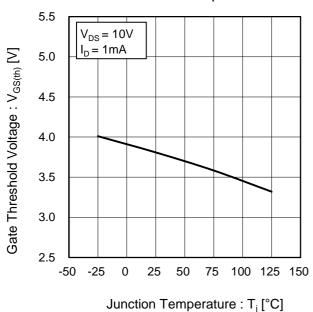
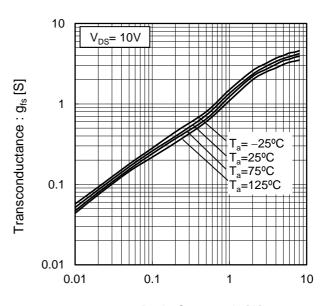


Fig.11 Transconductance vs. Drain Current



Drain Current : I_D [A]

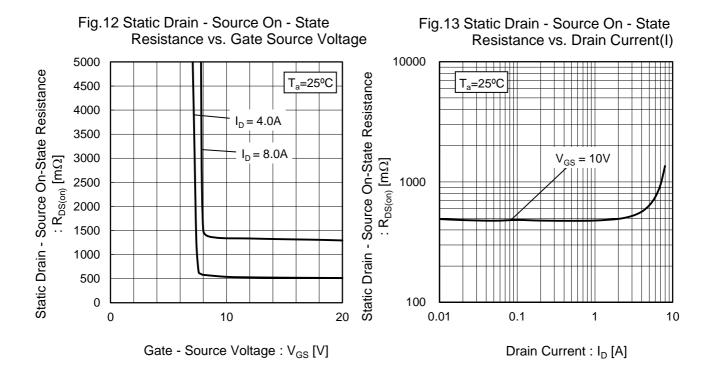
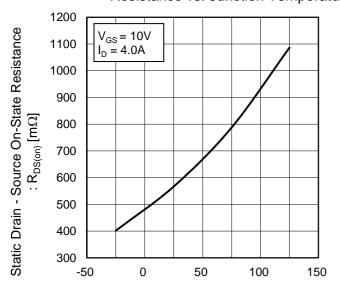


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature



Junction Temperature : T_i [°C]

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

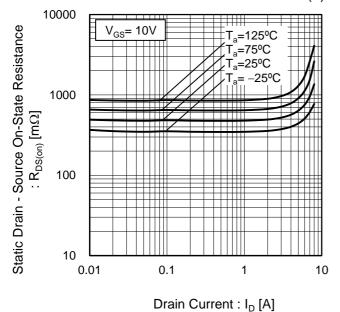
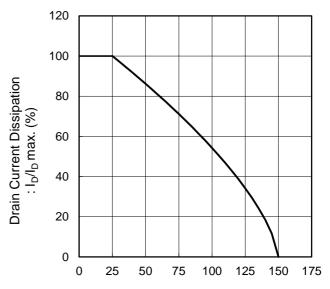
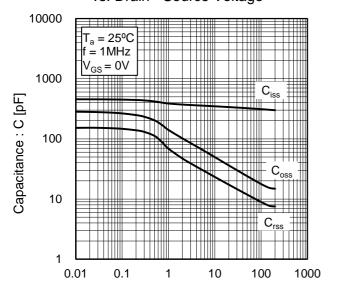


Fig.16 Drain Current Derating Curve



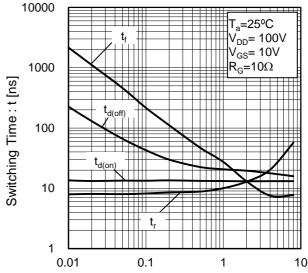
Junction Temperature : T_i [°C]

Fig.17 Typical Capacitance vs. Drain - Source Voltage



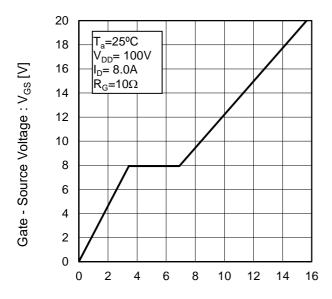
Drain - Source Voltage : V_{DS} [V]

Fig.18 Switching Characteristics

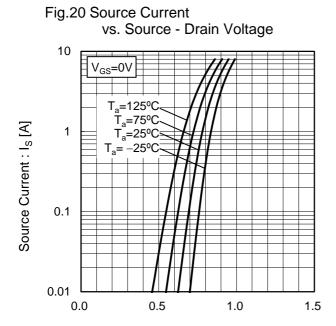


Drain Current: I_D [A]

Fig.19 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]



Source-Drain Voltage : V_{SD} [V]

Fig21 Reverse Recovery Time vs.Source Current

1000

T_a=25°C

di / dt = 100A / µs

V_{GS} = 0V

100

0.1

1 10

Source Current : I_s [A]

●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

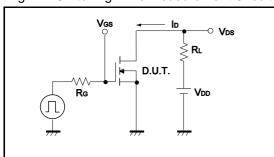


Fig.2-1 Gate Charge Measurement Circuit

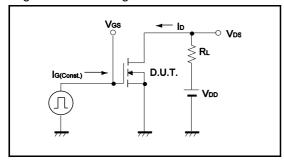


Fig.3-1 Avalanche Measurement Circuit

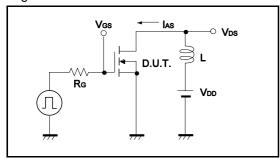


Fig.1-2 Switching Waveforms

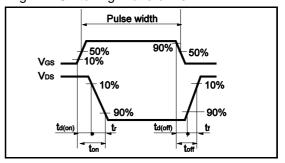


Fig.2-2 Gate Charge Waveform

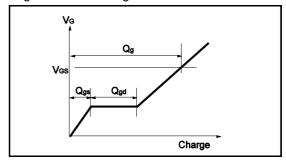
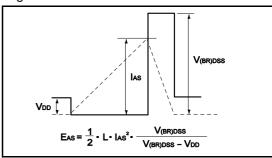
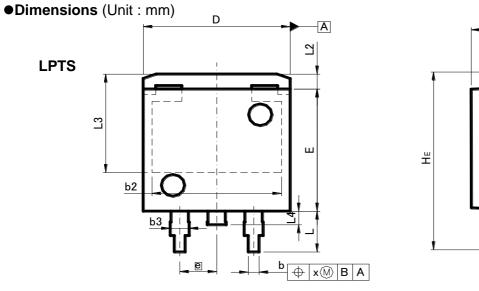
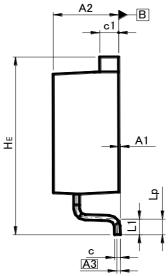
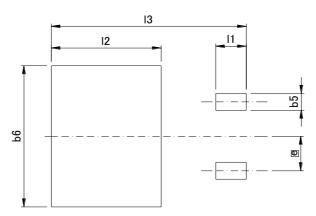


Fig.3-2 Avalanche Waveform









Patterm of terminal position areas

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0	0.012
A2	4.30	4.70	0.169	0.185
A3	0.5	25	0.	01
b	0.68	0.98	0.027	0.039
b2	8.	90	0.	35
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.	10
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.13
L1	0.90	1.50	0.035	0.059
L2	1.	10	0.0)43
L3	7.5	25	0.2	85
L4	1.	00	0.0	39
Lp	0.90	1.50	0.035	0.059
Х	_	0.25	_	0.01

DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
b5	_	1.23	İ	0.049
b6	-	10.40	ı	0.409
11	-	2.10	ı	0.083
12	-	7.55	-	0.297
13	_	13.40	_	0.528

Dimension in mm/inches

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JÁPAN	USA	EU	CHINA
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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
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